

## DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name; I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: **TFI Probe I/O Wrap Test Method**  
the specification of which:  
(check one)

☒ is attached hereto.

☐ was filed on \_\_\_\_\_, as Application Serial No. \_\_\_\_\_ and was amended on \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

**Prior Foreign Application(s):**

Number	Country	Day/Month/Year	Priority Claimed
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I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

**Prior U.S. Applications:**

Serial No.	Filing Date	Status
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

As a named inventor, I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: Mark F. Chadurjian (Reg. No. 30,739), Richard A. Henkler (Reg. No. 39,220), Richard M. Kotulak (Reg. No. 27,712), James M. Leas (Reg. No. 34,372), William D. Sabo (Reg. No. 27,465), Eugene I. Shkurko (Reg. No. 36,678), Robert A. Walsh (Reg. No. 26,516), Howard J. Walter, Jr. (Reg. No. 24,832), Christopher A. Hughes (Reg. No. 26,914), Edward A. Pennington (Reg. No. 32,588), John E. Hoel (Reg. No. 26,279), Joseph C. Redmond, Jr., (Reg. No. 18,753), George Vande Sande, Registration No. 17,276; Burton A. Amernick, Registration No. 24,852; Richard Wiener, Registration No. 18,741; Townsend M. Belser, Jr., Registration No. 22,956; Morris Liss, Registration No. 24,510; Martin Abramson, Registration No. 25,787; George R. Pettit, Registration No. 27,369; Elzbieta Chlopecka, Registration No. 32,767; Eric J. Franklin, Registration No. 37,134; Jeffri A. Kaminski, Reg. No. 42,709; and William E. Curry, Registration No. 43,572.

Send all correspondence to: Pollock, Vande Sande & Amernick, R.L.L.P.; PO Box 19088; Washington, D.C. 20036-3425  
Telephone calls should be directed to: Eric J. Franklin (202) 331-7111

(1) Inventor: Gobinda Das

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

6/30/00

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Express Mail Label No.: EL046034252US

IBM Docket No.: BUR9-1999-0278-US1

Citizenship: India

Post Office Address: Same as Residence

(2) Inventor: Franco Motika

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Residence: 145 Clove Branch Road; Hopewell Junction, NY 12533

Citizenship: USA

Post Office Address: Same as Residence

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## ASSIGNMENT

IBM Docket No.: BUR9-1999-0278-US1

Whereas, We,

Gobinda Das County of Dutchess	City of Hopewell Junction and state of New York
Franco Motika County of Dutchess	City of Hopewell Junction and state of New York

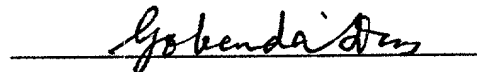
have invented certain improvements in:

## TFI PROBE I/O WRAP TEST METHOD

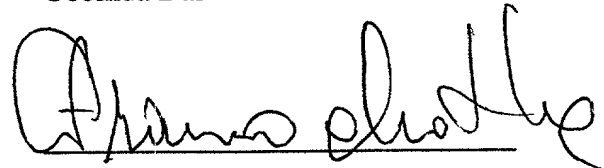
and have executed, respectively, a United States patent application therefor on

(1) 6/30, 2000 and (2) 6/29, 2000.

And whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504 (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor; Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, We the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns, and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

(1) Signed at (City) East Fishkill, N.Y.on (Date) 6/30/00

Gobinda Das

(2) Signed at (City) East Fishkill, N.Y.on (Date) June 29, 2000

Franco Motika